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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: GLENN ET AL. DOCKET NO.: W2K1016
SERIAL NO: 10/067,068 EXAMINER: CRUZ, L.
FILED: 02/06/2002 ART UNIT: 2827
TITLE: THIN INTEGRATED CIRCUIT PACKAGE HAVING AN OPTICALLY
TRANSPARENT WINDOW

Assistant Commissioner
for Patents
Washington, D.C. 20231

Weiss & Moy, P.C.
4204 North Brown Avenue
Scottsdale, Arizona 85251-3989

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August 30, 2002

I hereby certify that on the 30th day of August, 2002,
this correspondence is being deposited with the U.S.
Postal Service as first class mail in an envelope
addressed to: Assistant Commissioner for Patents,
Washington, D.C. 20231.



Jeffrey D. Moy

Dear Sir:

AMENDMENT LETTER

This is in response to the Office Action dated August 30, 2002
in regards to the above identified patent application. Please
amend the subject patent application as follows:

IN THE CLAIMS

✓
Please cancel Claims 15-20 without prejudice or disclaimer.

Please add the following new Claims:

New Claim 21. An optical integrated circuit, comprising:
a tape having a conductive pattern disposed on a surface thereof;

A' a die mounted to the tape and electrically coupled to the conductive pattern for providing an electronic function of the integrated circuit;

means surrounding the die and bonded to the tape for providing support;

means mounted over the die for allowing an optically active surface of the die to be accessible through the means mounted over the die; and

a plurality of external contacts electrically coupled to the conductive pattern for providing an electrical interface to the die.

New Claim 22. The optical integrated circuit of Claim 21, wherein the means surrounding the die is a thin metal support structure having an aperture for accepting the die.

New Claim 23. The optical integrated circuit of Claim 21, wherein the means surrounding the die is a thin epoxy film.

New Claim 24. The optical integrated circuit of Claim 21, wherein the means mounted over the die is bonded to the die by an optically transparent adhesive to form an integrated covered die, and further comprising an encapsulant disposed between the means surrounding and the covered die.

A' New Claim 25. The optical integrated circuit of Claim 21, wherein the means mounted over the die is bonded to a top surface of the means surrounding the die.

New Claim 26. The optical integrated circuit of Claim 21, wherein the means mounted over the die is a glass cover.

REMARKS

The Examiner has requested a restriction requirement directed to pending Claims 1-20. The Examiner alleges that the application contains claims directed to the following distinct species of the claimed invention: Claims 1-14 (Invention I) drawn to a semiconductor device; and Claims 15-20 (Invention II) drawn to a method of making a semiconductor device. The Examiner alleges that Invention I and Invention II claims define patentably distinct inventions.

We respectfully traverse this restriction requirement. Applicants respectfully submit that the Claims are interrelated to one another and should be prosecuted as part of the same application. The claims relate to a semiconductor package and a method of making the semiconductor package. However, in order to fully respond to the Examiner's restriction requirements, Applicants have elect to prosecute Claims 1-14 (Invention I) in the subject patent application. Claims 15-20 have been cancelled without prejudice or disclaimer and replaced with new Claims 21-26 which are drawn to the same species as Invention I.

No additional fees should be incurred by the addition of the new Claims since the total number of Claims being prosecuted remain at 20. If there are any fees incurred by this Amendment Letter, please deduct them from our Deposit Account NO. 23-0830.

Respectfully submitted,



Jeffrey D. Moy
Reg. No. 39,307
Attorney for Applicants

Weiss & Moy, P.C.
4204 N. Brown Ave.
Scottsdale, AZ 85251
(480) 994-8888 (Phone)
(480) 947-2663 (Fax)